



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:
Padhi, et al.

Serial No.: 10/678,003

Filed: October 2, 2003

For: Homogeneous Copper-Palladium
Alloy Plating For Enhancement of
Electro-Migration Resistance In
Interconnects

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

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§ Group Art Unit: 1753
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§ Examiner: Unknown
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CERTIFICATE OF MAILING 37 CFR 1.8	
I hereby certify that this correspondence is being deposited on December <u>03</u> , 2004, with the United States Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450 Alexandria, VA 22313-1450.	
<u>Dec. 03, 2004</u> Date	<u>Ari Pramudji</u> Signature

STATUS INQUIRY

More than 12 months have passed since

☒ the filing of this application on October 2, 2003.

No communication has been received from the Patent and Trademark Office
indicating action on this application or response.

Kindly advise the undersigned of the present status of this application. A
stamped return-addressed envelope is provided.

Respectfully submitted,

Ari Pramudji

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